Supplier Name: Contact Info: Form/Declaration Type: Created on:

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - ROHS and IEC 62474 DB

Distribute - RoHS and IE 06/14/2022

Details for "BQ25895RTWT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
BQ25895RTWT	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	RTW 24	4x4x0.75	49.4

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.78349	99.997575	999976	1.587299	15873
Copper and Its Alloys	Iron	7439-89-6	0.000003	0.000383	4	0.000006	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000002	0.000255	3	0.000004	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000001	0.000128	1	0.000002	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000002	0.000255	3	0.000004	0
Precious Metals	Silver	7440-22-4	0.000011	0.001404	14	0.000022	0
Sub-Total			0.783509	100	1000000	1.587337	15873
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.154335	79.999986	800000	2.338606	23386
Thermoplastics	Epoxy	85954-11-6	0.288584	20.000014	200000	0.584652	5847
Sub-Total			1.442919	100	1000000	2.923258	29233
Lead Frame					•		
Copper and Its Alloys	Copper	7440-50-8	28.2808	97.52	975200	57.29503	572950
Copper and Its Alloys	Iron	7439-89-6	0.667	2.3	23000	1.351298	13513
Copper and Its Alloys	Phosphorus	7723-14-0	0.0087	0.03	300	0.017626	176
Zinc and Its Alloys	Zinc	7440-66-6	0.0435	0.15	1500	0.088128	881
Sub-Total			29	100	1000000	58.752082	587521
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.85608	95.12	951200	1.734361	17344
Precious Metals	Gold	7440-57-5	0.00702	0.78	7800	0.014222	142
Precious Metals	Palladium	7440-05-3	0.0369	4.1	41000	0.074757	748
Sub-Total			0.9	100	1000000	1.82334	18233
Mold Compound	-				•		
Other Inorganic Materials	Fused Silica	60676-86-0	12.356075	88.000002	880000	25.032591	250326
Other Organic Materials	Chlorine	7782-50-5	0.00014	0.000997	10	0.000284	3
Other Plastics and Rubber	Carbon Black	1333-86-4	0.042123	0.3	3000	0.085338	853
Thermoplastics	Ероху	85954-11-6	1.642656	11.699001	116990	3.327912	33279
Sub-Total			14.040994	100	1000000	28.446125	284461
Semiconductor Device	-				•		
Ceramics / Glass	Doped Silicon	7440-21-3	3.192531	100	1000000	6.467857	64679
Sub-Total			3.192531	100	1000000	6.467857	64679
Total			49.359953			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo

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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pob-Free." These TI semiconductor products are also fully compliant with ADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.